L Number	Hits	Search Text	DB	Time stamp
1	0	661/233.ccls.	USPAT; US-PGPUB	2003/11/04 14:14
2	248	361/233.ccls.	USPAT; US-PGPUB	2003/11/04 14:14
3	493	361/234.ccls.	USPAT; US-PGPUB	2003/11/04 14:15
4	57709	force near2 (sens$3 detect$3 control$3 monitor$2)	USPAT; US-PGPUB	2003/11/04 14:15
5	28	361/234.ccls. and (force near2 (sens$3 detect$3 control$3 monitor$2))	USPAT; US-PGPUB	2003/11/04 14:15
6	328	361/235.ccls.	USPAT; US-PGPUB	2003/11/04 14:15
7	2595	electrostatic near2 chuck	USPAT; US-PGPUB	2003/11/04 14:16
8	93	(force near2 (sens$3 detect$3 control$3 monitor$2)) and (electrostatic near2 chuck)	USPAT; US-PGPUB	2003/11/04 14:16
9	2376	(electrostatic near2 chuck) and (workpiece wafer)	USPAT; US-PGPUB	2003/11/04 14:16
10	115	((electrostatic near2 chuck) and (workpiece wafer)) and current near2 (detect$3 sens$3 monitor$2)	USPAT; US-PGPUB	2003/11/04 14:18
11	1095	(electrostatic near2 chuck) and plasma near2 process	USPAT; US-PGPUB	2003/11/04 14:17
12	64	((electrostatic near2 chuck) and plasma near2 process) and current near2 (detect$3 sens$3 monitor$2)	USPAT; US-PGPUB	2003/11/04 14:18
13	377	(electrostatic near2 chuck) and wafer same (dechuck$2 releas$2)	USPAT; US-PGPUB	2003/11/04 14:18
14	334	279/128.ccls.	USPAT; US-PGPUB	2003/11/04 14:29
15	182	279/128.ccls. and (electrostatic near2 chuck)	USPAT; US-PGPUB	2003/11/04 14:29
16	19	279/128.ccls. and (force near2 (sens$3 detect$3 control$3 monitor$2))	USPAT; US-PGPUB	2003/11/04 14:29